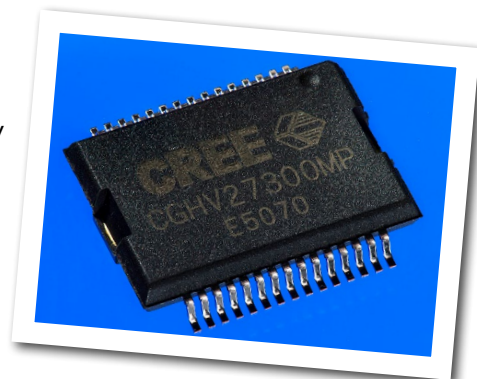


# CGHV27300MP

**300 W, 2300-2700 MHz, GaN HEMT for LTE**

Cree's CGHV27300MP is a gallium nitride (GaN) high electron mobility transistor (HEMT) is designed specifically for high efficiency, high gain and wide bandwidth capabilities, which makes the CGHV27300MP ideal for 2.3-2.7 GHz LTE and BWA amplifier applications. The transistor is input matched and supplied in an overmold package.



PN: CGHV27300MP

## Typical Performance Over 2.5 - 2.7 GHz ( $T_c = 25^\circ\text{C}$ ) of Demonstration Amplifier

Parameter	2.5 GHz	2.6 GHz	2.7 GHz	Units
Gain @ 47.8 dBm	16	16	16	dB
ACLR @ 47.8 dBm	-35.0	-37.0	-34.0	dBc
Drain Efficiency @ 47.8 dBm	34.7	32.1	32.7	%

**Note:**

Measured in the CGHV27300MP-TB amplifier circuit, under WCDMA 3GPP test model 1, 64 DPCH, 45% clipping, PAR = 7.5 dB @ 0.01% Probability on CCDF.

## Features

- 2.3 - 2.7 GHz Operation
- 16 dB Gain
- -35 dBc ACLR at 60 W  $P_{AVE}$
- 33% Efficiency at 60 W  $P_{AVE}$
- High Degree of DPD Correction Can be Applied





## Absolute Maximum Ratings (not simultaneous)

Parameter	Symbol	Rating	Units	Units
Drain-Source Voltage	$V_{DS}$	125	Volts	25°C
Gate-to-Source Voltage	$V_{GS}$	-10, +2	Volts	25°C
Storage Temperature	$T_{STG}$	-65, +150	°C	
Operating Junction Temperature	$T_J$	225	°C	
Maximum Forward Gate Current	$I_{GMAX}$	42	mA	25°C
Maximum Drain Current <sup>1</sup>	$I_{DMAX}$	15.6	A	25°C
Soldering Temperature <sup>2</sup>	$T_S$	245	°C	
Thermal Resistance, Junction to Case <sup>3</sup>	$R_{JC}$	1.03	°C/W	85°C, $P_{DISS} = 125$ W
Case Operating Temperature <sup>4</sup>	$T_C$	-40, +150	°C	30 seconds

Note:

<sup>1</sup> Current limit for long term, reliable operation.

<sup>2</sup> Refer to the Application Note on soldering at <http://www.cree.com/rf/document-library>

<sup>3</sup> Measured for the CGHV27300MP

<sup>4</sup> See also, the Power Dissipation De-rating Curve on Page 4

## Electrical Characteristics ( $T_C = 25^\circ\text{C}$ )

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
<b>DC Characteristics<sup>1</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	-3.8	-3.0	-2.3	$V_{DC}$	$V_{DS} = 10$ V, $I_D = 42$ mA
Gate Quiescent Voltage	$V_{GS(Q)}$	-	-2.7	-	$V_{DC}$	$V_{DS} = 50$ V, $I_D = 1.0$ A
Saturated Drain Current <sup>2</sup>	$I_{DS}$	31.2	37.4	-	A	$V_{DS} = 6.0$ V, $V_{GS} = 2.0$ V
Drain-Source Breakdown Voltage	$V_{BR}$	125	-	-	$V_{DC}$	$V_{GS} = -8$ V, $I_D = 42$ mA
<b>RF Characteristics<sup>5</sup> (<math>T_C = 25^\circ\text{C}</math>, <math>F_0 = 2.7</math> GHz unless otherwise noted)</b>						
Saturated Output Power <sup>3,4</sup>	$P_{SAT}$	-	300	-	W	$V_{DD} = 50$ V, $I_{DQ} = 1.0$ A
Pulsed Drain Efficiency <sup>3</sup>	$\eta$	-	65	-	%	$V_{DD} = 50$ V, $I_{DQ} = 1.0$ A, $P_{OUT} = P_{SAT}$
Gain <sup>6</sup>	G	-	16	-	dB	$V_{DD} = 50$ V, $I_{DQ} = 1.0$ A, $P_{OUT} = 47.8$ dBm
WCDMA Linearity <sup>6</sup>	ACLR	-	-35	-	dBc	$V_{DD} = 50$ V, $I_{DQ} = 1.0$ A, $P_{OUT} = 47.8$ dBm
Drain Efficiency <sup>6</sup>	$\eta$	-	32	-	%	$V_{DD} = 50$ V, $I_{DQ} = 1.0$ A, $P_{OUT} = 47.8$ dBm
Output Mismatch Stress <sup>3</sup>	VSWR	-	-	10 : 1	$\Psi$	No damage at all phase angles, $V_{DD} = 50$ V, $I_{DQ} = 1.0$ A, $P_{OUT} = 200$ W Pulsed
<b>Dynamic Characteristics</b>						
Input Capacitance <sup>7</sup>	$C_{GS}$	-	-	-	pF	$V_{DS} = 50$ V, $V_{gs} = -8$ V, $f = 1$ MHz
Output Capacitance <sup>7</sup>	$C_{DS}$	-	-	-	pF	$V_{DS} = 50$ V, $V_{gs} = -8$ V, $f = 1$ MHz
Feedback Capacitance	$C_{GD}$	-	-	-	pF	$V_{DS} = 50$ V, $V_{gs} = -8$ V, $f = 1$ MHz

Notes:

<sup>1</sup> Measured on wafer prior to packaging.

<sup>2</sup> Scaled from PCM data.

<sup>3</sup> Pulse Width = 100  $\mu$ S, Duty Cycle = 10%

<sup>4</sup>  $P_{SAT}$  is defined as  $I_G = 4$  mA peak.

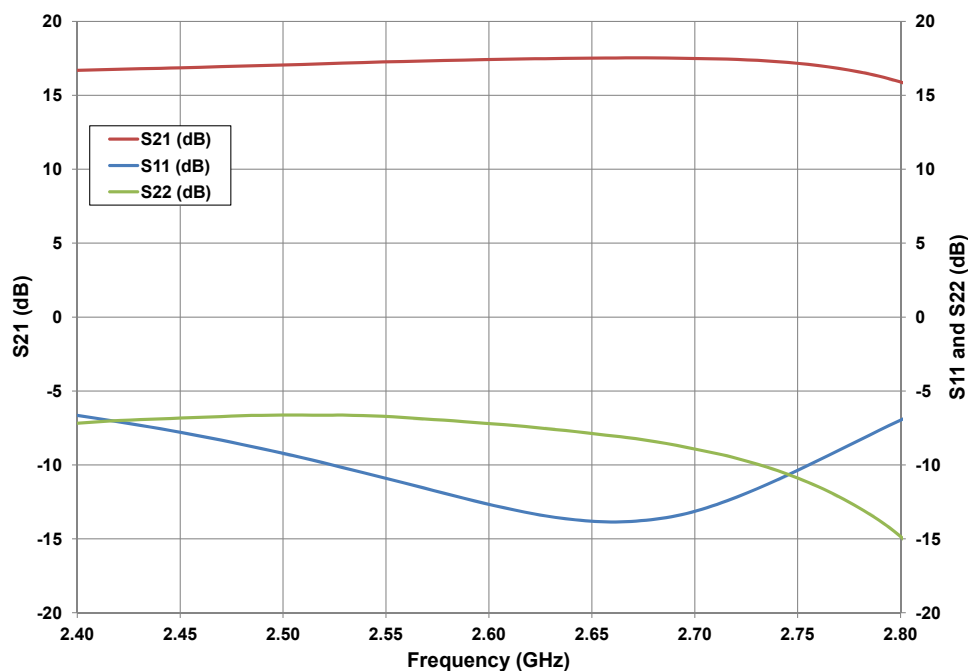
<sup>5</sup> Measured in CGHV27300MP-TB.

<sup>6</sup> Single Carrier WCDMA, 3GPP Test Model 1, 64 DPCH, 45% Clipping, PAR = 7.5 dB @ 0.01% Probability on CCDF.

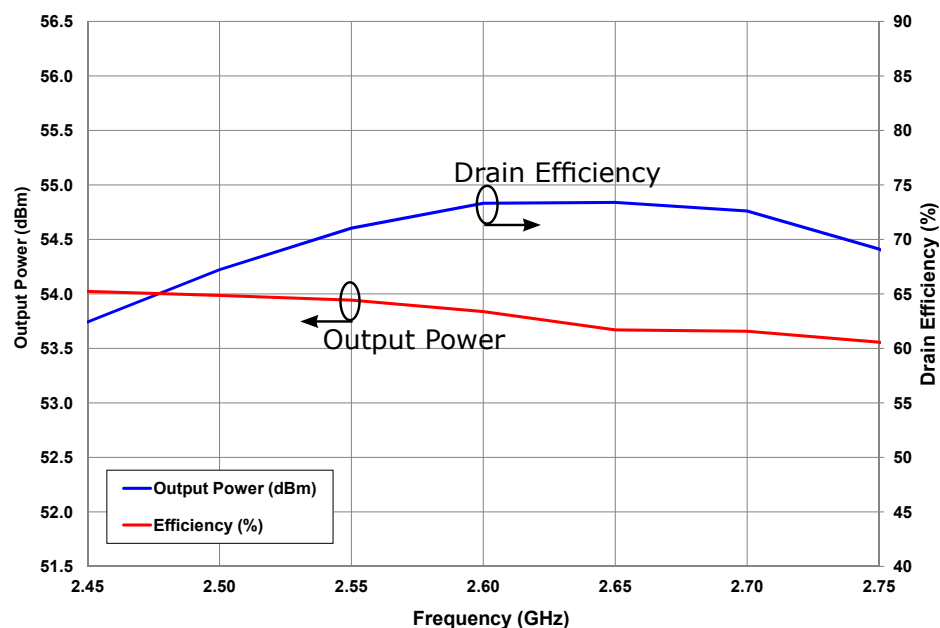
<sup>7</sup> Includes package and internal matching components.

## Typical Performance

**Figure 1. - Small Signal Gain and Return Losses vs Frequency for the CGHV27300MP measured in CGHV27300-TB Amplifier Circuit**  
 $V_{DD} = 50 \text{ V}$ ,  $I_{DQ} = 1.0 \text{ A}$

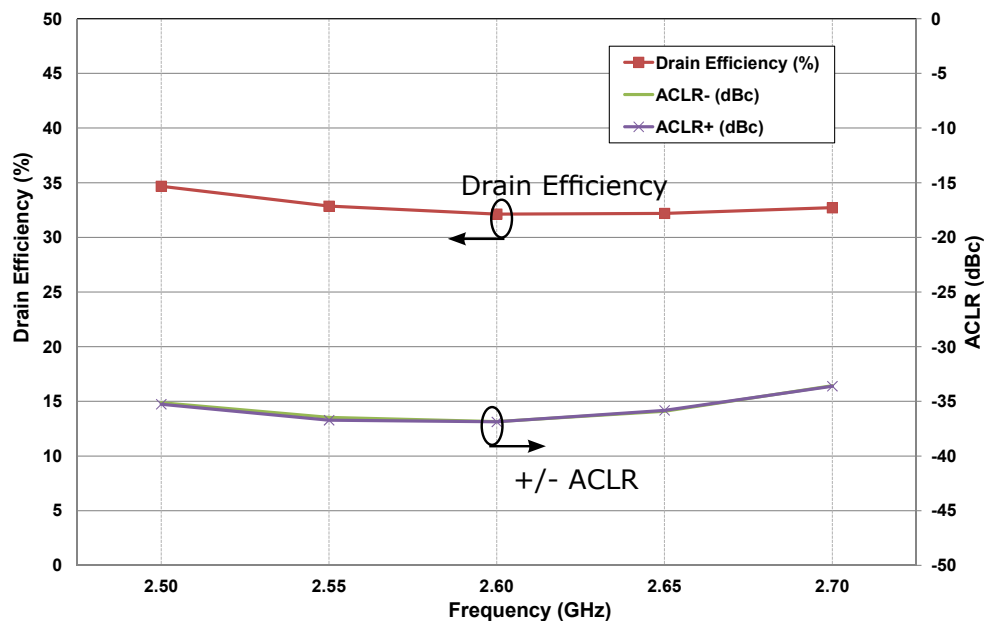


**Figure 2. - Typical Output Power and Drain Efficiency of the CGHV27300MP measured in CGHV27300MP-TB Amplifier Circuit.**  
 $V_{DS} = 50 \text{ V}$ ,  $I_{DS} = 1.0 \text{ A}$ , Pulse Width 100  $\mu\text{s}$ , Duty Cycle 10%

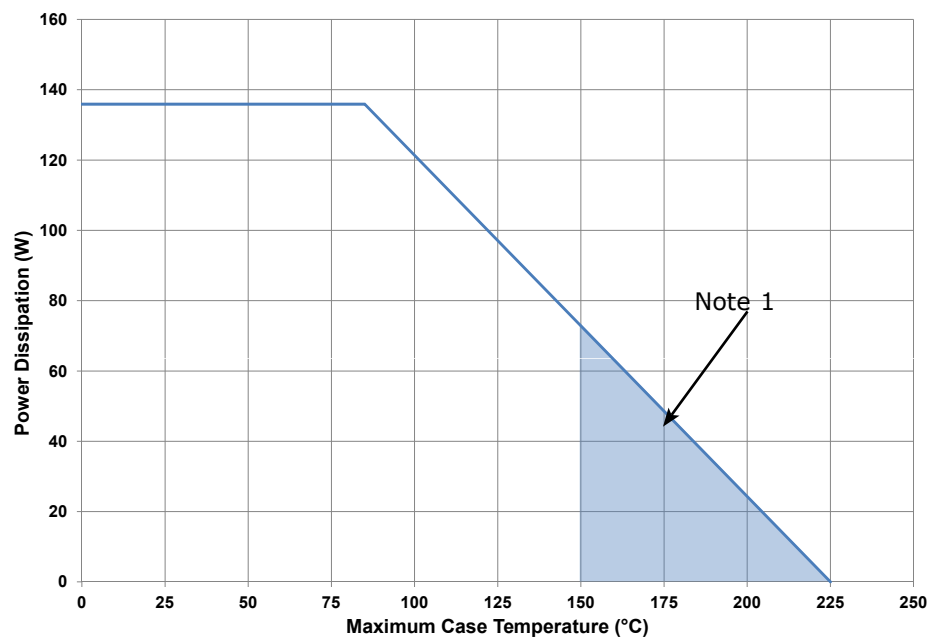


## Typical Performance

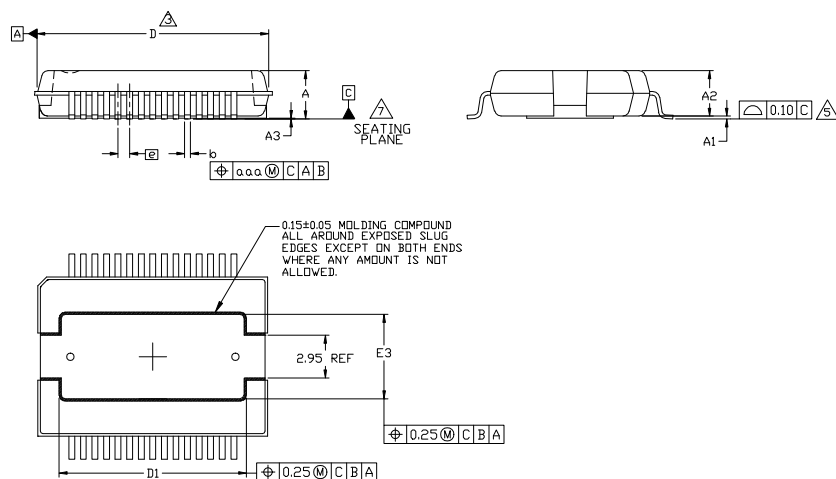
**Figure 3. - WCDMA 5MHz Single Carrier - Gain, Drain Efficiency, and ACLR**  
**CGHV27300MP measured in CGHV27300-TB Amplifier Circuit**  
 $V_{DD} = 50\text{ V}$ ,  $I_{DQ} = 1.0\text{ A}$



**Figure 4. - Power Dissipation Derating Curve**



Note 1. Area exceeds Maximum Case Operating Temperature (See Page 2).



A SEATING PLANE IS DEFINED BY LEAD TIPS ONLY.

SYMBOL	COMMON DIMENSIONS			Notes
	MIN.	NOM.	MAX.	
A	—	—	3.60	
A1	0.10	0.20	0.30	
A2	3.00	3.15	3.30	
A3	0	0.05	0.10	
aaa		0.20		
b	0.35		0.48	
D1	9.00	15.90 BSC		3
E		14.20 BSC	13.00	
E1		11.00 BSC		4
E3	5.80		6.20	
e		0.80 BSC		

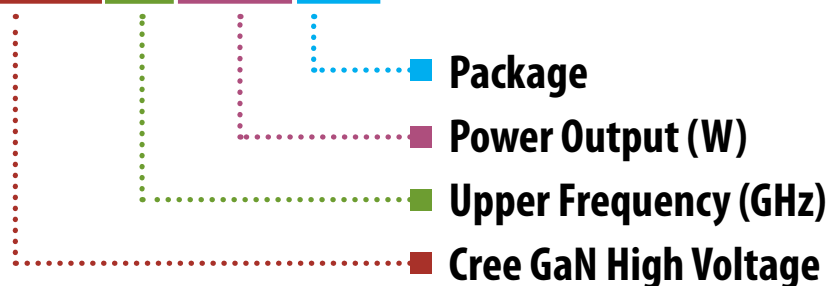
PIN	FUNCTION
1	NC
2	NC
3	NC
4	RF INPUT
5	RF INPUT
6	RF INPUT
7	RF INPUT
8	RF INPUT
9	RF INPUT
10	RF INPUT
11	RF INPUT
12	RF INPUT
13	NC
14	NC
15	NC
16	VIDEO BIAS FEED
17	VIDEO BIAS FEED
18	NC
19	RF OUTPUT
20	RF OUTPUT
21	RF OUTPUT
22	RF OUTPUT
23	RF OUTPUT
24	RF OUTPUT
25	RF OUTPUT
26	RF OUTPUT
27	RF OUTPUT
28	NC
29	VIDEO BIAS FEED
30	VIDEO BIAS FEED

Pin	Input/Output
1	NC
2	NC
3	NC
4	RF IN
5	RF IN
6	RF IN
7	RF IN
8	RF IN
9	RF IN
10	RF IN
11	RF IN
12	RF IN
13	NC
14	NC
15	NC

Pin	Input/Output
16	VIDEO BIAS FEED
17	VIDEO BIAS FEED
18	NC
19	RF OUT
20	RF OUT
21	RF OUT
22	RF OUT
23	RF OUT
24	RF OUT
25	RF OUT
26	RF OUT
27	RF OUT
28	NC
29	VIDEO BIAS FEED
30	VIDEO BIAS FEED

## Part Number System

# CGHV27300MP



Parameter	Value	Units
Upper Frequency <sup>1</sup>	2.7	GHz
Power Output	300	W
Package	Plastic Overmold	-

**Table 1.**

**Note<sup>1</sup>:** Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Character Code	Code Value
A	0
B	1
C	2
D	3
E	4
F	5
G	6
H	7
J	8
K	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz

**Table 2.**



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